

XPedite7301

Intel® Core™i7 Processor-Based XMC Module

- › Intel® Core™i7-610E, -620LE, and -620UE processors
- › Dual-core with hyper-threading technology
- › XMC module
- › Conduction or air cooling
- › Up to 8 GB of DDR3-1066 ECC SDRAM in two channels
- › 8 MB NOR boot flash
- › Up to 16 GB of NAND flash
- › Two x4 or one x8 PCI Express XMC interface
- › Gigabit Ethernet port with integrated magnetics
- › Four USB 2.0 high-speed ports
- › Two SATA 3.0 Gb/s ports
- › Two RS-232/RS-422/RS-485 serial ports
- › DVI-D video
- › Audio line in/out port
- › Linux BSP
- › VxWorks BSP
- › QNX Neutrino BSP
- › Green Hills INTEGRITY BSP
- › Microsoft Windows XP/Vista drivers



XPedite7301

The XPedite7301 is a high-performance, low-power XMC module based on the Intel® Core™i7 processor and Intel QM57 chipset. With one x8 or two x4 PCI Express ports and a Gigabit Ethernet port, the XPedite7301 is ideal for high-bandwidth data-processing applications.

The XPedite7301 accommodates up to 8 GB of DDR3 ECC SDRAM to support memory-intensive applications and hosts numerous I/O ports including Gigabit Ethernet, USB 2.0, SATA, and RS-232/RS-422/RS-485.

Wind River VxWorks, QNX Neutrino, Linux, and Green Hills INTEGRITY Board Support Packages (BSPs) are available for the XPedite7301, as well as Windows drivers.

X-ES

Extreme Engineering Solutions

...Always Fast

Extreme Engineering Solutions

3225 Deming Way, Suite 120 • Middleton, WI 53562
 Phone: 608.833.1155 • Fax: 608.827.6171
 sales@xes-inc.com • <http://www.xes-inc.com>

Processor

- Intel® Core™i7 processor operating at 2.53, 2.0, or 1.06 GHz
- Dual-core with hyper-threading technology
- Intel QM57 chipset
- Dual channel integrated memory controller
- Integrated graphics controller
- 4 MB of shared cache

Memory

- Up to 8 GB of DDR3-1066 ECC SDRAM
- 8 MB NOR boot flash
- Up to 16 GB of NAND flash

P14 PMC Interface

- Two USB 2.0 ports
- Two RS-232/RS-422/RS-485 ports
- One 10/100/1000BASE-T Ethernet port
- Four GPIO Signals
- One audio in/out port

P15 XMC Interface

- One x8 or two x4 PCI Express links

P16 XMC Interface

- One DVI-D display
- Two USB 2.0 ports
- Two SATA 3.0 Gb/s ports
- One x4 PCI Express link

Software Support

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Windows drivers

Physical Characteristics

- XMC form factor
- Dimensions: 149 mm x 74 mm, 10-mm stacking height

Environmental Requirements

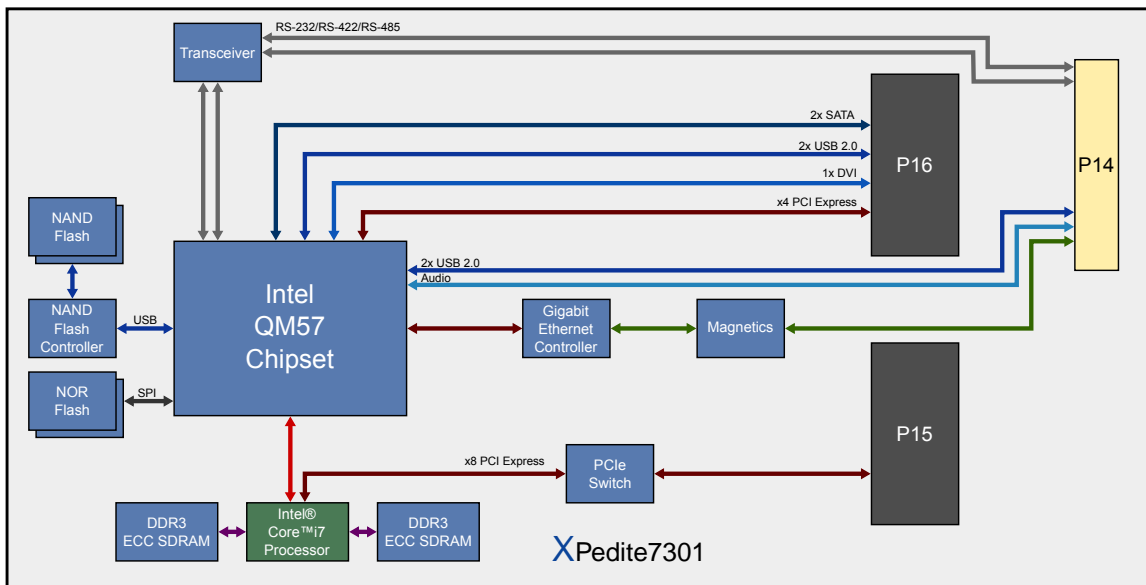
Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): Level 1, Level 2, Level 3, Level 4, Level 5
- Humidity: 0% to 95% non-condensing
- Storage temperature: -55 to 105 °C

Power Requirements (Estimate)

- 20 W (1.06 GHz)

Ruggedization Level	Level 1	Level 2	Level 3	Level 4	Level 5
Cooling Method	Standard Air-Cooled	Extended Air-Cooled	Rugged Air-Cooled	Conduction-Cooled	Conduction-Cooled
Operating Temperature	0 to +55 °C	0 to +65 °C	-40 to +70 °C	-40 to +70 °C	-40 to +85 °C
Vibration	0.002 g ² /Hz	0.002 g ² /Hz	0.04 g ² /Hz	0.1 g ² /Hz	0.1 g ² /Hz
Shock	20 g	20 g	40 g	40 g	40 g
Storage Temperature	-40 to +105 °C	-40 to +105 °C	-55 to +105 °C	-55 to +105 °C	-55 to +105 °C



Distributor: **NeoMore** 23 rue des Poiriers F-78370 PLAISIR FRANCE +33 1 30 64 15 81 www.neomore.com

